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(54) Title: DEVICE FOR HOLDING WAFER SHAPED ARTICLES

(57) Abstract: A device for holding wafer-shaped articles, such as semiconductor wafers, is equipped with a series of pins that are brought into contact with a peripheral edge of the wafer-shaped article, under control of a common gear ring or a series of conjointly operated gear sectors. In the regions of the gear ring or gear sectors engaging the pin assemblies, those elements are designed to yield more readily than other regions of the gear ring or gear sectors, to accommodate differential thermal expansion of the chuck components in the vicinity of the pin assemblies.

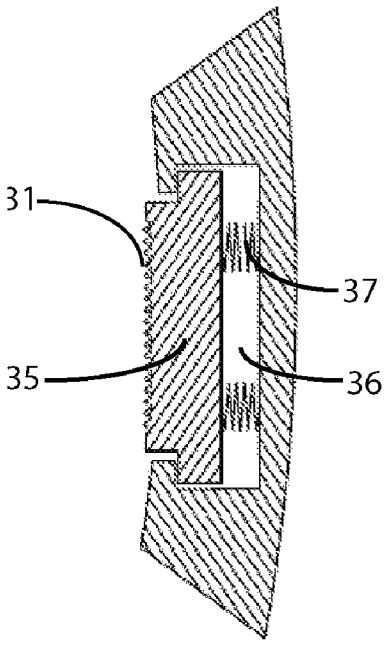


Fig. 5

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